

STN	Integrácia softvérového nástroja (FDI) Časť 100: Profily Kmeňové protokoly	STN EN IEC 62769-100 18 4012
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Field device integration (FDI) - Part 100: Profiles - Generic protocols

Táto norma obsahuje anglickú verziu európskej normy.
This standard includes the English version of the European Standard.

Táto norma bola oznámená vo Vestníku ÚNMS SR č. 01/21

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**Field device integration (FDI) - Part 100: Profiles - Generic
protocols
(IEC 62769-100:2020)**

Intégration des appareils de terrain (FDI) - Partie 100:
Profils - Protocoles génériques
(IEC 62769-100:2020)

Feldgeräteintegration (FDI) - Teil 100: Profile - Allgemeine
Protokolle
(IEC 62769-100:2020)

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EN IEC 62769-100:2020 (E)**European foreword**

The text of document 65E/739/FDIS, future edition 1 of IEC 62769-100, prepared by SC 65E "Devices and integration in enterprise systems" of IEC/TC 65 "Industrial-process measurement, control and automation" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 62769-100:2020.

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- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2021-07-29
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Annex ZA (normative)

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<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 61804	series	Function blocks (FB) for process control and electronic device description language (EDDL)	EN IEC 61804	series
IEC 61804-3	-	Devices and integration in enterprise systems - Function blocks (FB) for process control and electronic device description language (EDDL) - Part 3: EDDL syntax and semantics	EN IEC 61804-3	-
IEC 62541-100	2015	OPC Unified Architecture - Part 100: Device Interface	EN 62541-100	2015
IEC 62769-2	-	Field Device Integration (FDI) - Part 2: FDI Client	-	-
IEC 62769-4	-	Field Device Integration (FDI) - Part 4: FDI Packages	-	-
IEC 62769-5	-	Field Device Integration (FDI) - Part 5: FDI Information Model	-	-
IEC 62769-7	-	Field Device Integration (FDI) - Part 7: FDI Communication Devices	-	-



IEC 62769-100

Edition 1.0 2020-09

INTERNATIONAL STANDARD

NORME INTERNATIONALE

**Field device integration (FDI) –
Part 100: Profiles – Generic protocols**

**Intégration des appareils de terrain (FDI) –
Partie 100: Profils – Protocoles génériques**



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IEC 62769-100

Edition 1.0 2020-09

INTERNATIONAL STANDARD

NORME INTERNATIONALE

**Field device integration (FDI) –
Part 100: Profiles – Generic protocols**

**Intégration des appareils de terrain (FDI) –
Partie 100: Profils – Protocoles génériques**

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FIELD DEVICE INTEGRATION (FDI) –**Part 100: Profiles – Generic protocols****FOREWORD**

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FCG TS62769-100 Edition 1.1, *Field Device Integration Part 100: Profiles – Generic Protocols*, a specification of the FieldComm Group, PROFIBUS Nutzerorganisation e. V., OPC Foundation and FDT Group, serves as a basis for the elaboration of this standard.

The text of this International Standard is based on the following documents:

FDIS	Report on voting
65E/739/FDIS	65E/743/RVD

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 62769 series, published under the general title *Field Device Integration (FDI)*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

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- amended.

FIELD DEVICE INTEGRATION (FDI) –

Part 100: Profiles – Generic protocols

1 Scope

This part of IEC 62769 specifies an FDI profile of IEC 62769 for generic protocols. That means that all interfaces are defined, and a host can add support for more protocols without changing its implementation. Nevertheless, there are some protocol-specific definitions (PSD) that need to be specified per protocol using this profile. Annex C specifies what PSDs need to be defined per protocol so that FDI Device Packages, FDI Communication Packages for Gateways and FDI Communication Servers, FDI Communication Servers, Gateways and Devices supporting such a protocol can work together in a host not aware about this specific protocol.

NOTE A host not using an FDI Communication Server but a proprietary mechanism for communication defines its own means to deal with this profile to support several protocols without changing its implementation. This is specific to the proprietary way how the communication driver is bound to the host.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 61804 (all parts), *Function blocks (FB) for process control and Electronic Device Description Language (EDDL)*

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IEC 62541-100:2015, *OPC Unified Architecture – Part 100: OPC UA for Devices*

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